

DATASHEET



KEY ADVANTAGES



High quality liquid cooling of the GPU



Heat dissipation increased up to 10 times as compared to the air-cooling



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Thermally-tested and quality guaranteed. Low ΔT^o between the chip and inlet coolant temperatures is assured



High efficient deformational cutting technology for microfins (0.25mm x 2.7mm) manufacturing



Designed for Gigabyte GeForce RTX™ 5090



Only non-corrosive materials (Copper, Stainless Steel, Plastic)

The Comino liquid-cooling system is based on the deformational cutting technology that allows to transfer more heat from the source than you would normally expect with direct liquid cooling.

This unique technology allows to create a copper fin as thin as 0.1mm with 0.1mm channel and 3mm height. In Comino solution microfins are optimized for low pressure drop with the thickness of 0.25mm, channel - 0.25mm and 2.7mm height.

Large increase (up to 12 times) of the waterblock surface area that contacts with the coolant allows faster heat dissipation. It prevents thermal throttling of CPU and GPU keeping temperatures within a safe range even at 24/7 operation in harsh environment.

This advantage makes our waterblocks extremely efficient (low ΔT°) and cost-effective.



Fullcover Waterblock cools the GPU, GDDR, and the VRM altogether



Single PCI Design

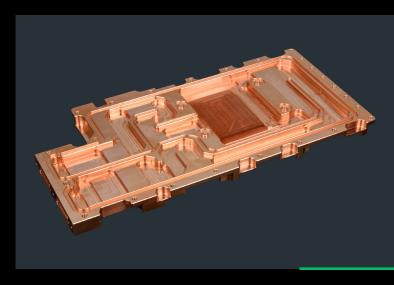


Fittings on the Back — Server Ready



90° Adapter Option — Workstation Ready





Release date

May, 25

WCB GPU (Gigabyte 50900C) Backplate Kit

OVERALL DIMENSIONS

WCB GPU (Gigabyte 50900C) Core Kit

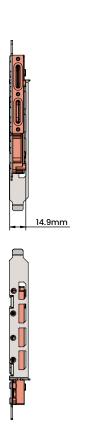
Core Block

8740

ID Name Release date ID Name

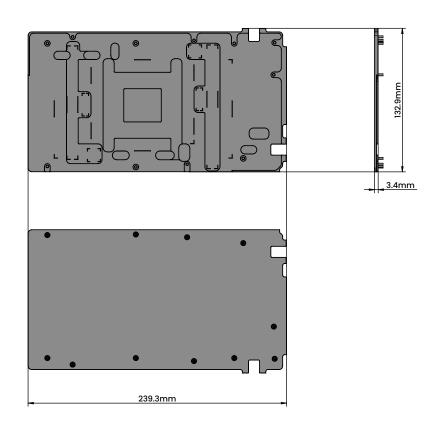
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Backplate Options

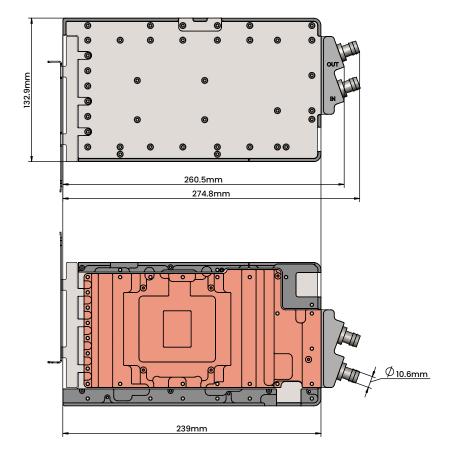
8742



OVERALL DIMENSIONS

Kit Options

ID	Name	Release date
8740	WCB GPU (Gigabyte 50900C) Core Kit	Apr, 25
8741	WCB GPU (Gigabyte 5090OC) Frame Kit	Apr, 25
8743	WCB GPU (Gigabyte 50900C) Retail Kit	Feb, 25
8744	WCB GPU (Gigabyte 50900C) Adapter single Kit	Feb, 25







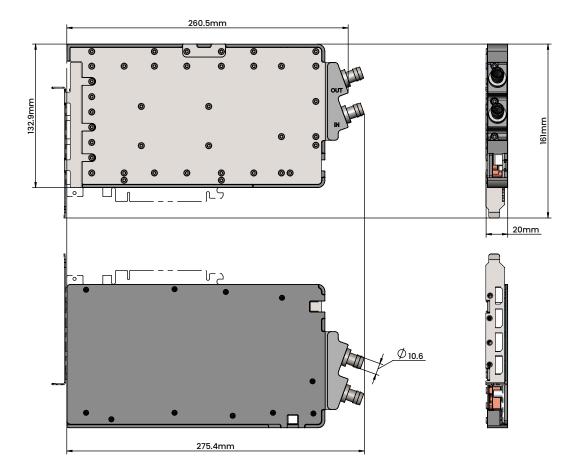




OVERALL DIMENSIONS

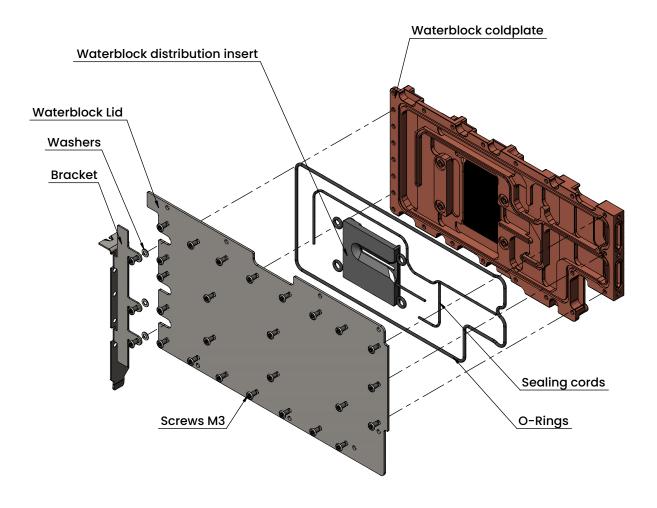
GPU Water Cooling Block Set

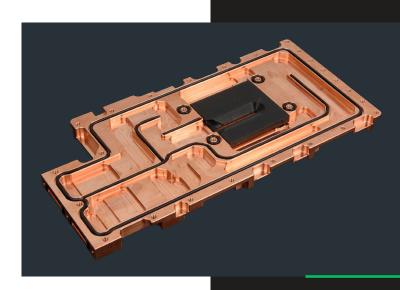
ID	Name		Release date May, 25	
		o GPU WCB for Gigabyte 5090, Cu-Steel, k Backplate, Angular Adapter 2x G1/4"		
	8740	WCB GPU (Gigabyte 50900C) Core Kit	Apr, 25	
8706	8741	WCB GPU (Gigabyte 50900C) Frame Kit	Apr, 25	
	8743	WCB GPU (Gigabyte 50900C) Retail Kit	Feb, 25	
	8744	WCB GPU (Gigabyte 50900C) Adapter single Kit	Feb, 25	
	8742	WCB GPU (Gigabyte 5090OC) Backplate Kit	May, 25	

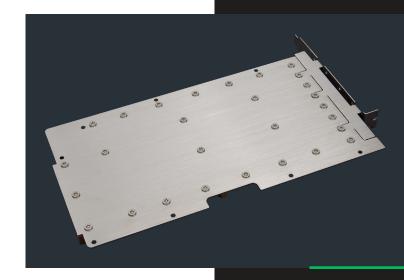




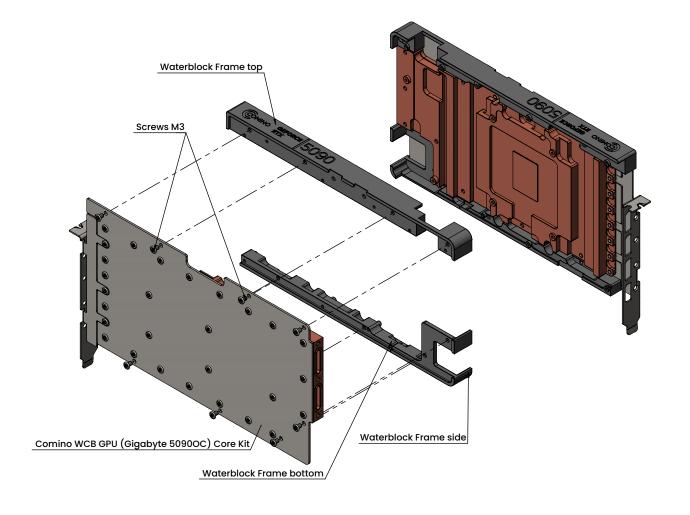






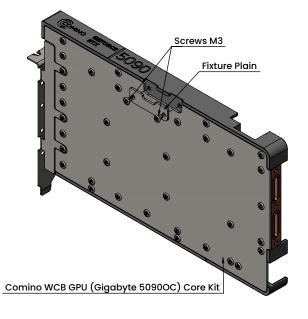


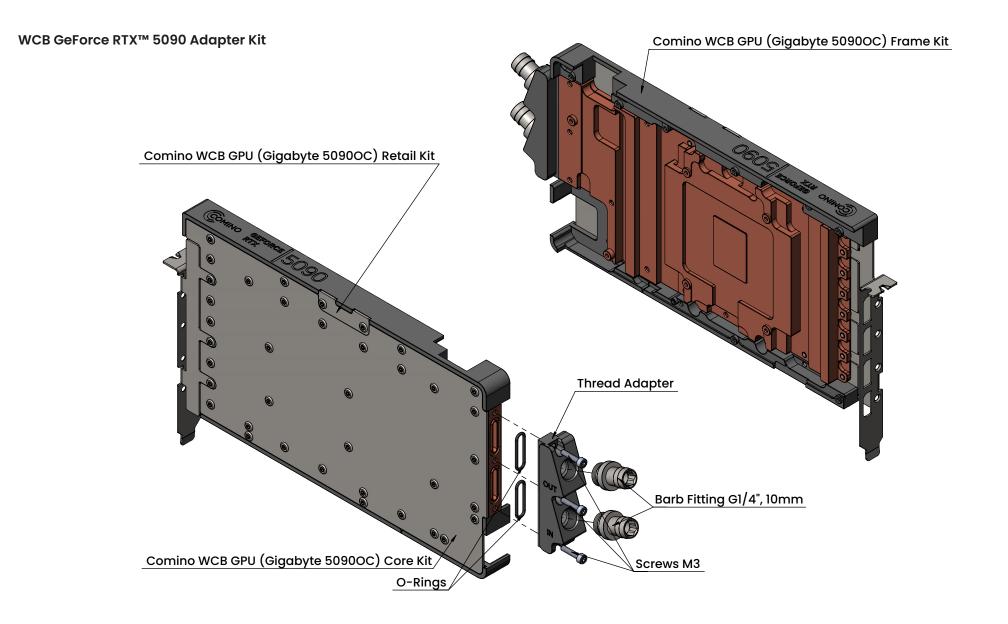
WCB GeForce RTX™ 5090 Frame Kit



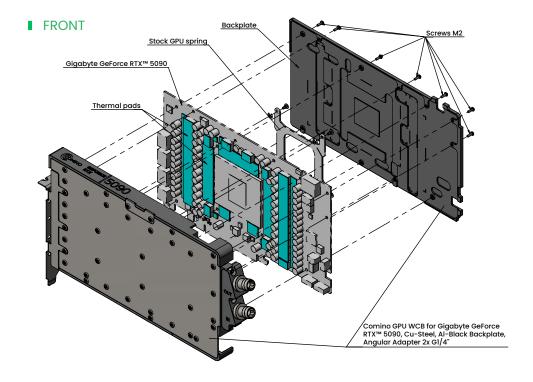


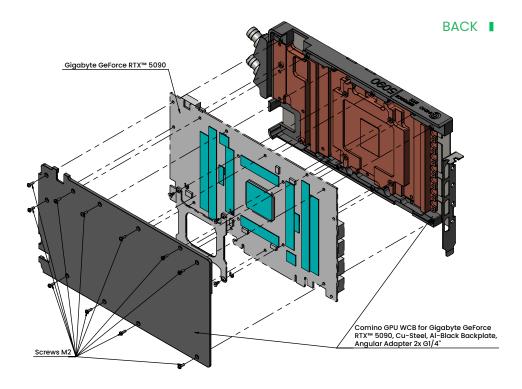
WCB GeForce RTX™ 5090 Retail Kit

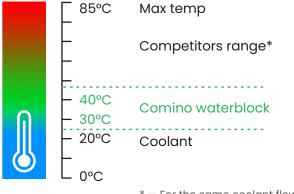




Comino GPU WCB for GeForce RTX™ 5090, Cu-Steel, Al-Black Backplate, Side Adapter 2x G1/4"



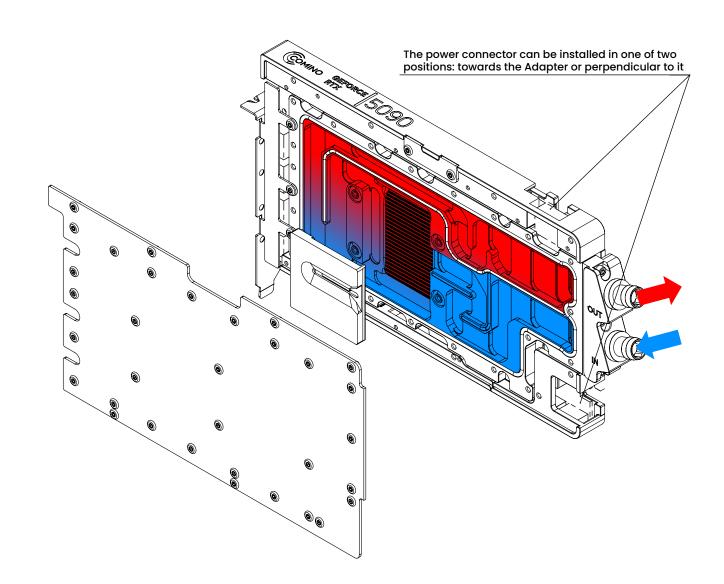




* - For the same coolant flow

Comino waterblock technology ensures low ΔT° between the chip and inlet coolant temperatures.

- At coolant temperature of 20°C, the temperature of the chips with Comino waterblocks will be 30°-40°C.
- The temperature of the chips with competitors waterblocks for the same coolant flow might rise up to 85°C.



Waterblock thermal resistance (°C/W) and coolant pressure drop (Pa) between inlet and outlet of waterblock vs coolant flow rate (I/min).

R (°C/W) vs Flow (lpm), dP (Pa) vs Flow (l/min)

0.2000

0.1500

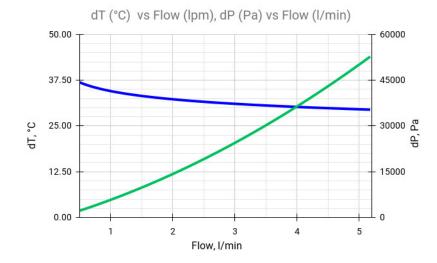
0.1000

0.0000

1 2 3 4 5

Flow, l/min

Temperature rise of GPU processor p-n junction relatively to coolant inlet temperature and coolant pressure drop (Pa) between inlet and outlet of waterblock vs coolant flow rate (I/min)



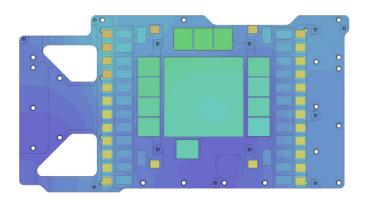
AMD RADEON™ PRO W7900

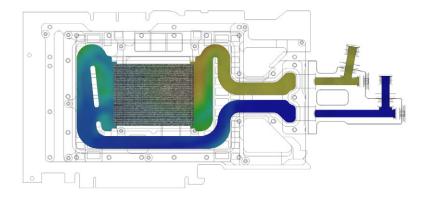
dP, Pa

WE KNOW HOW TO BEAT THE HEAT

Comino provides RnD upon request, including product design with a series of complex thermodynamic calculations and a variety of stress tests supported by thermal analysis.

- Tailored liquid-cooling system and solution for your needs.
- OEM & ODM cooperation. Thermal design, prototyping, PoC, manufacturing, QA, supply.
- Creating a unique customization of hardware components and liquid-cooling systems.
- Design & Manufacturing of devices and cooling components for range of industry applications from scratch.





ADDITIONAL INFORMATION

Check the compatibility and find the composition of the kit on the waterblock product page:

https://faq.comino.com/en/waterblocks/main





CONTACTS

For more product information visit: www.comino.com

Email us: info@comino.com

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